PSI Roadshow in Q3,2025

Nov. 2025

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- Information as to those factors that could cause actual results to vary can be found in PSI’s Annual or Quarterly Report filed with Taiwan Stock Exchange Corporation (TWSE) and such other documents as PSI may file with, or submit to the TWSE from time to time.

- Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

- The numbers of the presentation are prepared under IFRS.

Agenda

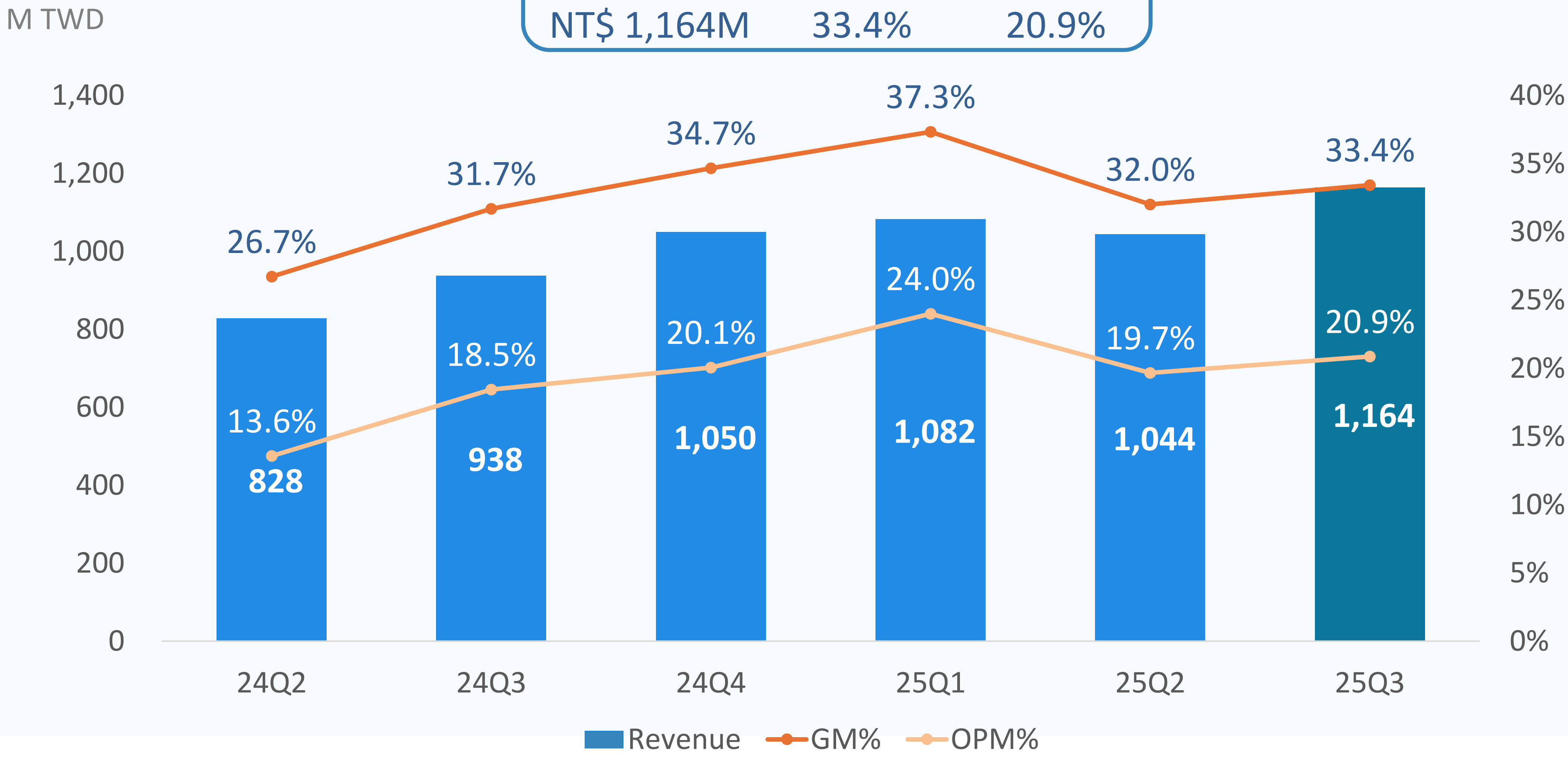
- Q3 Finance Results
- Semi Industry Outlook
- Reclaim wafer Demand Drivers and Market Share Forecast
- Potential Drivers from 12” Silicon and SiC Thinning Business
- Long Term Expansion Plan
- Key Messages

Q3 Finance Results

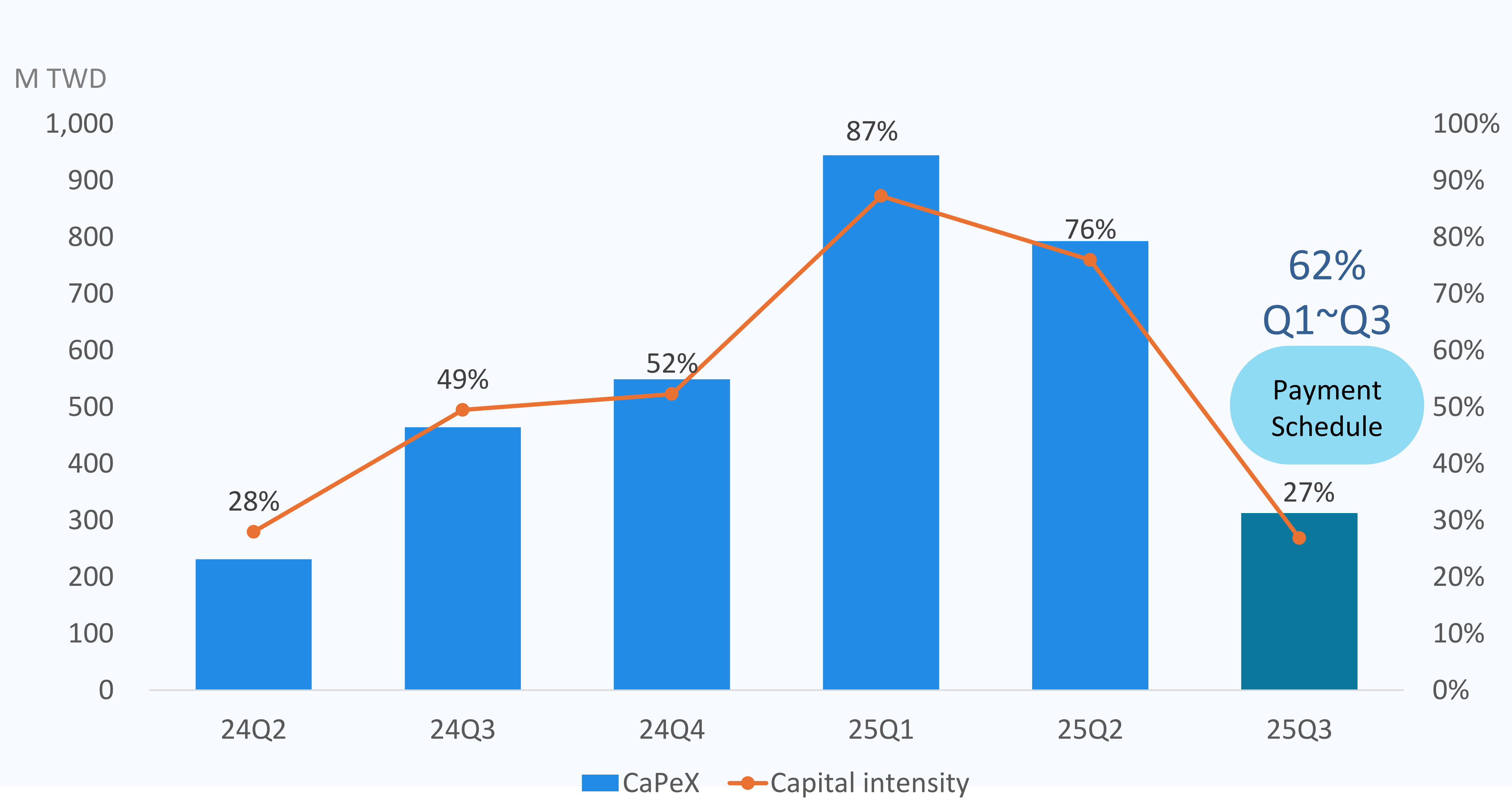
Financial Highlights

2025Q3

Revenue	GPM	OPM
NT$ 1,164M	33.4%	20.9%



Scaling In-Time to Meet Customer’s Need

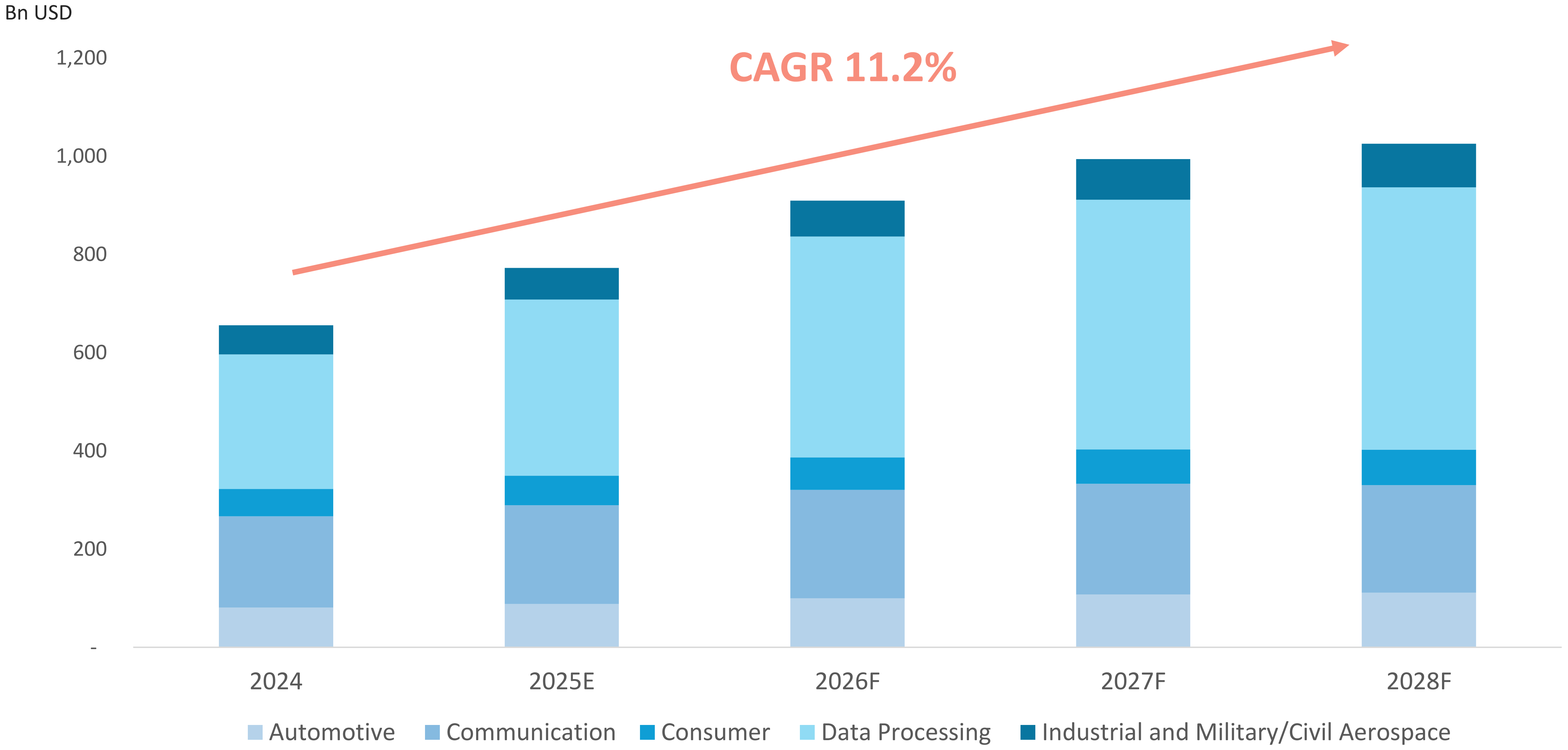


Financial Matrix

Item	2025Q1	2025Q2	2025Q3
Shipment (Kpcs, 12"-equiv. Wafer)	2,099	2,292	2,531
Net Revenue (US$ Millions)	33	34	38
Net Revenue (NT$ Millions)	1,082	1,044	1,164
Gross Margin	37.3%	32.0%	33.4%
Operating Margin	24.0%	19.7%	20.9%
Net Profit Margin	21.3%	9.5%	17.3%
EPS (NT$)	1.34	0.58	1.17
ROE (annualized)	21.2%	15.6%	17.8%
Operating Cash Flow (NT$ M)	426	304	261
Capital Expenditures (NT$ M)	-944	-793	-313
Free Cash Flow (NT$ M)	-518	-489	-52

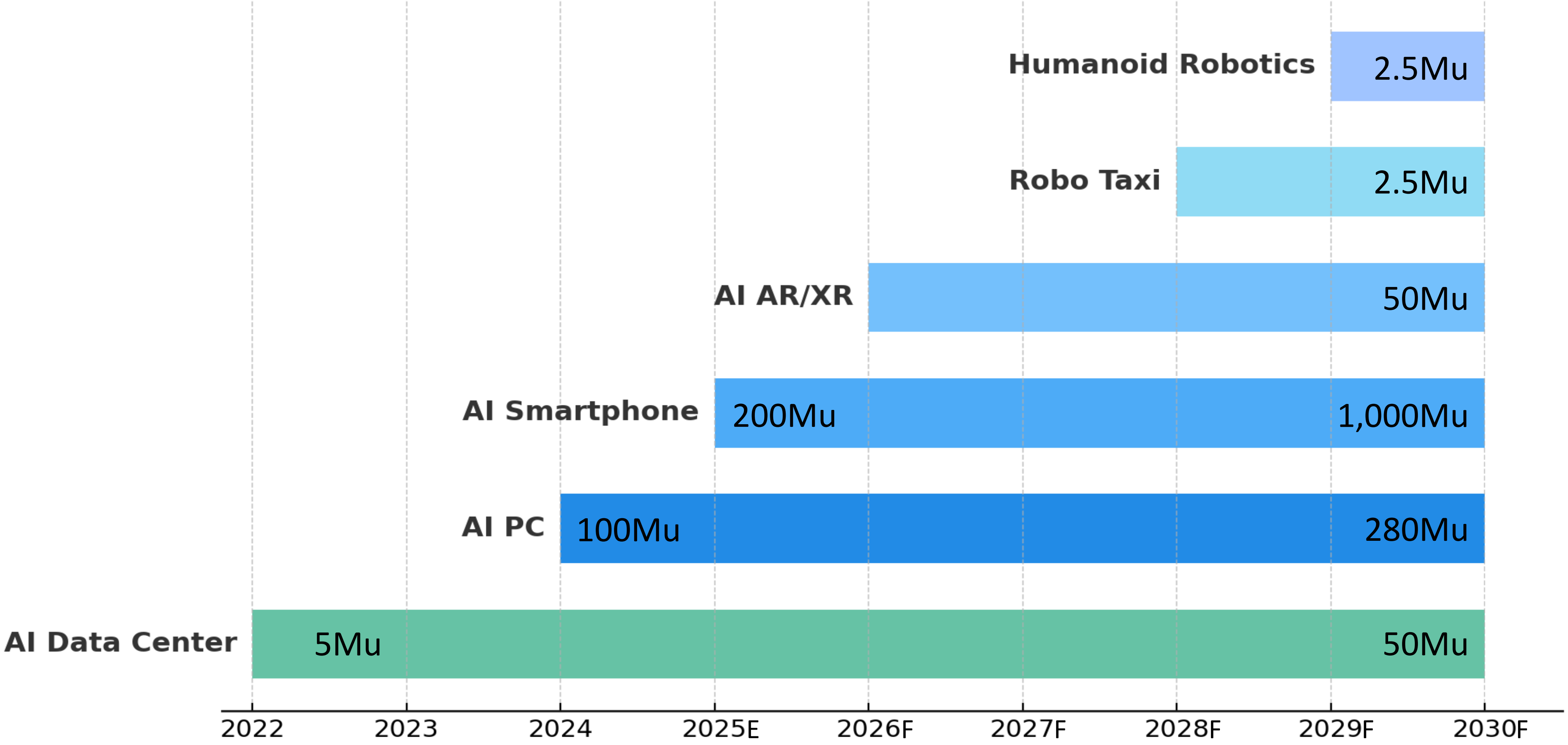
Semi Industry Outlook

AI to Drive Semiconductor Market to $1 Trillion



Source: Gartner

AI From Centralized Cloud to Distributed Edge

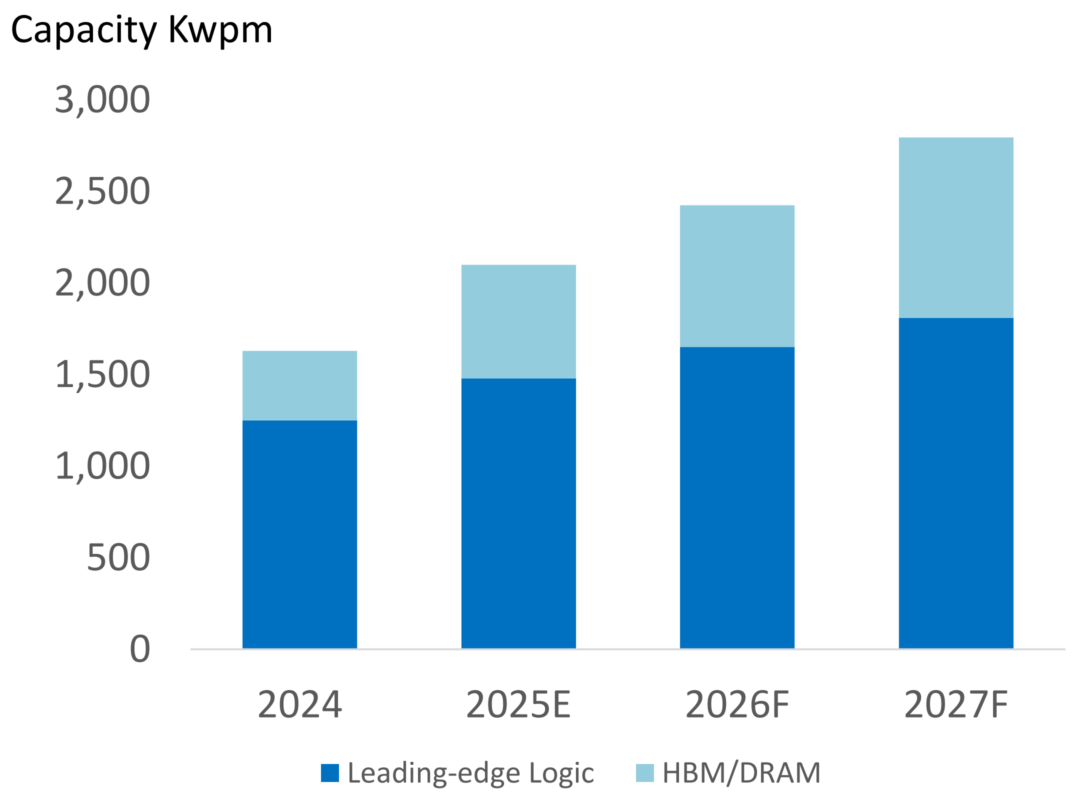


Source: WSTS, IDC, TSMC

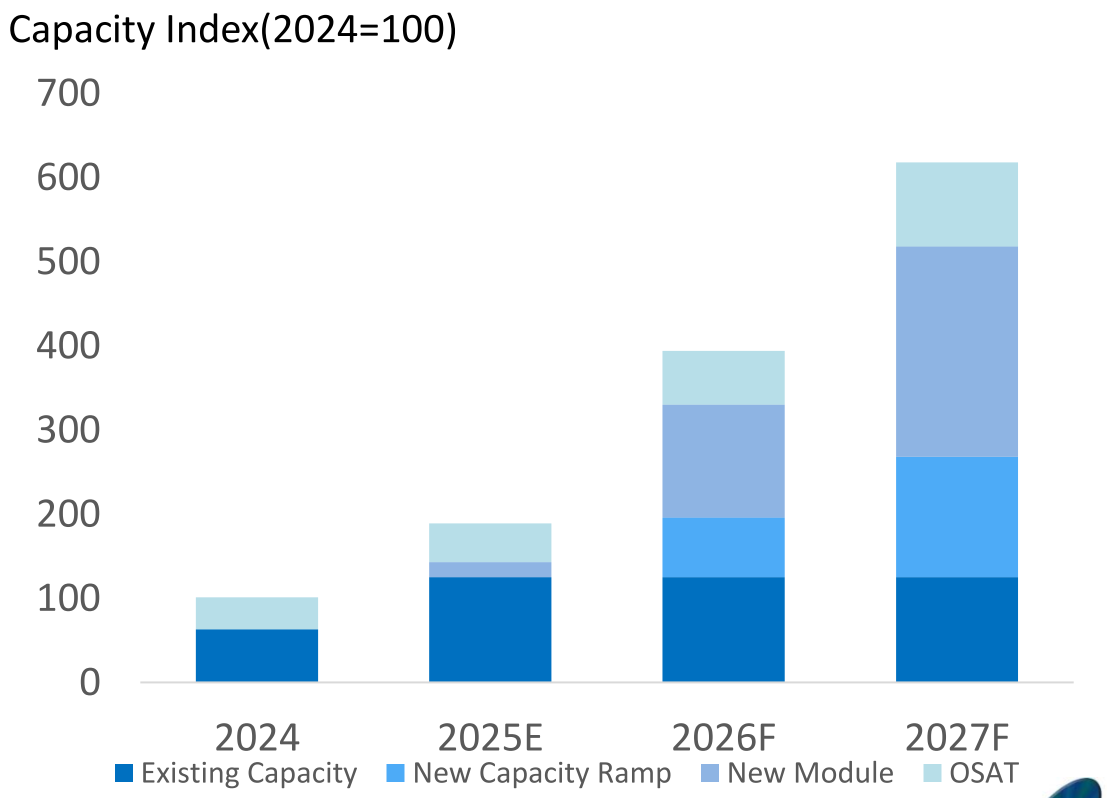
Reclaim Wafer Drivers and Market Share Forecast

Wafer Demand Two Growth Drivers

Front-End Capacity Growing



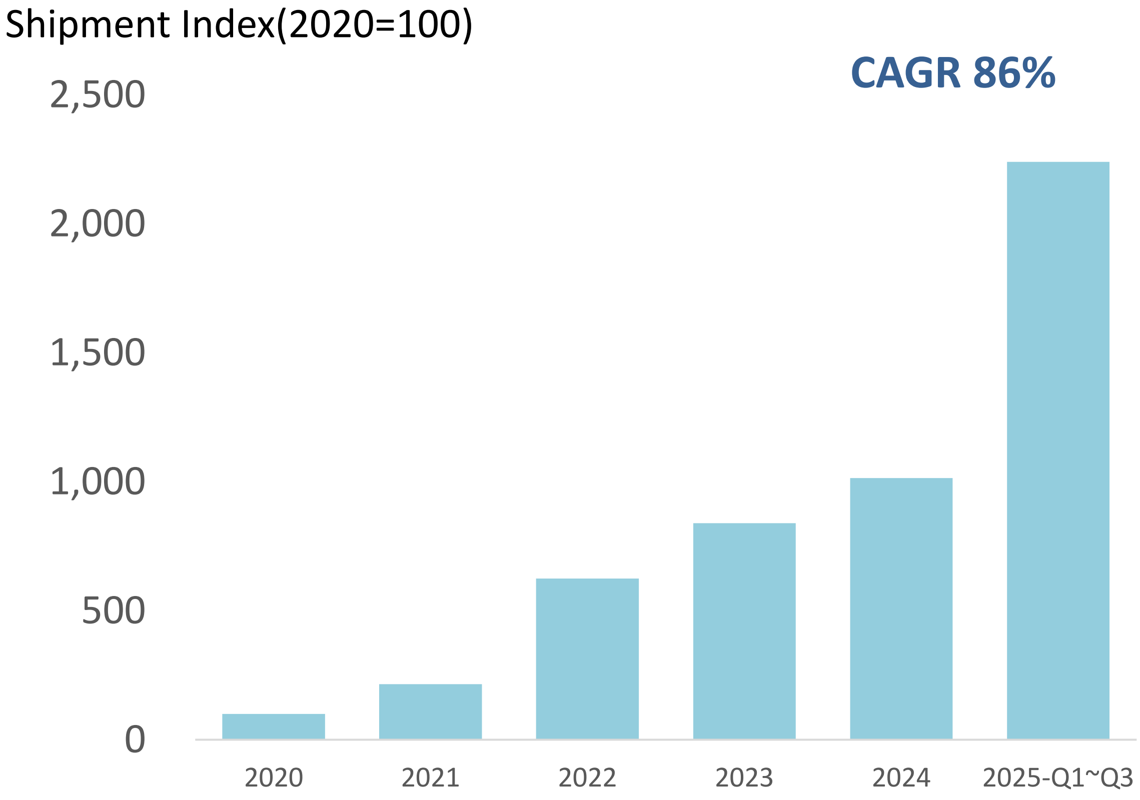
Adv. Packaging Volume Ramping up



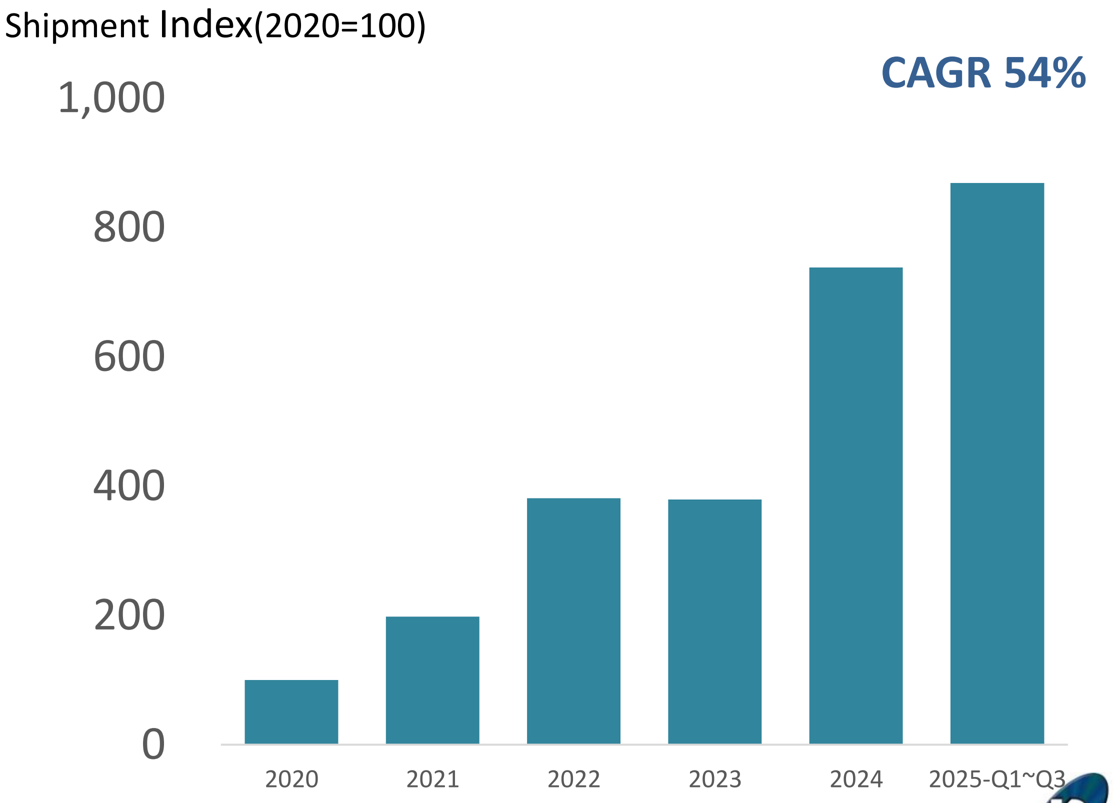
Source: company data, TrendForce PSI

PSI's Emerging Driving Vectors

Reclaim wafer for HBM/DRAM



Reclaim wafer for Adv. Packaging



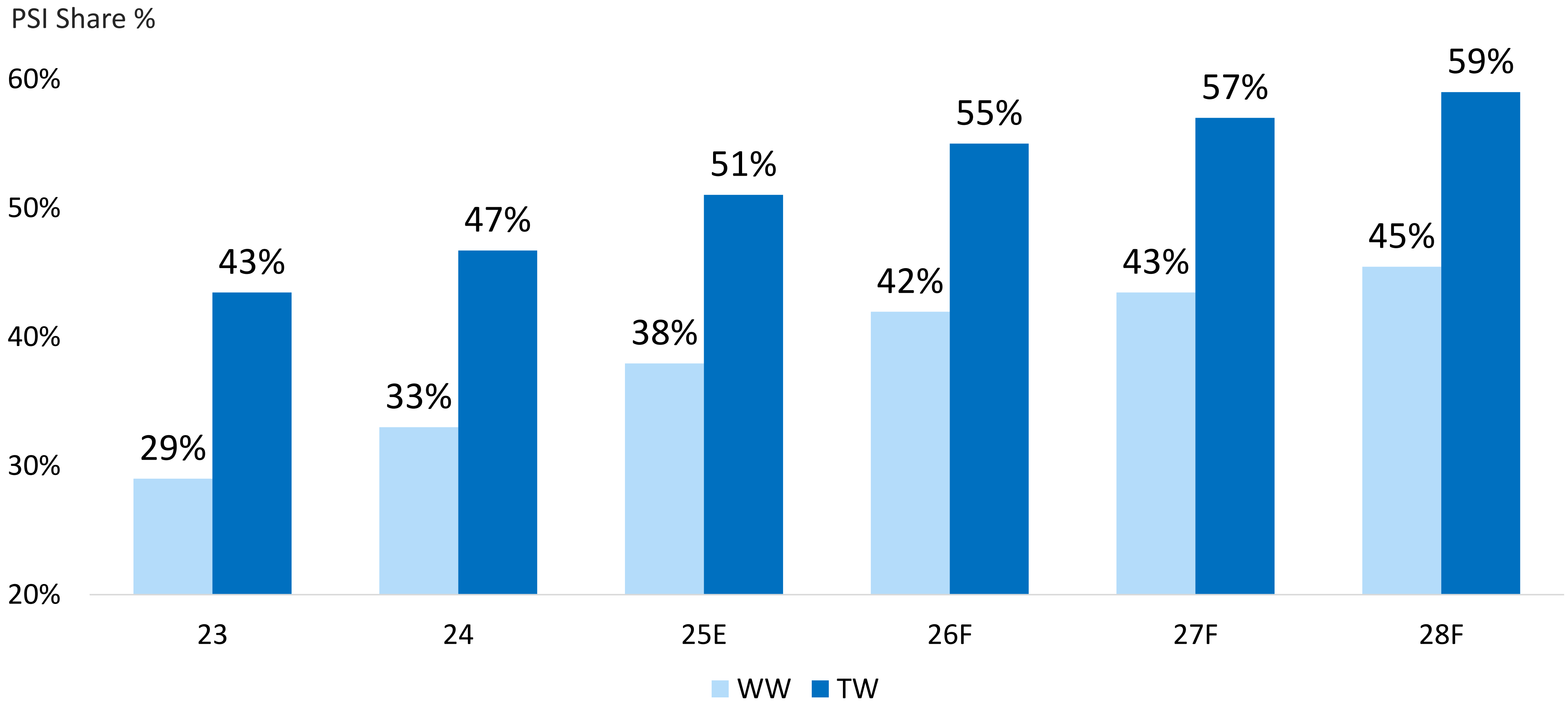
Source: company data, PSI

Strategic CapEx & Investment Directions

- **12-inch Reclaim Capacity Expansion**
  Proactively expanding capacity to fulfill robust demand for high-spec products, thereby securing long-term order stability.
- **SiC Wafering Technology R&D**
  Investing in Silicon Carbide wafering and processing technology, which is the present and future of AI.

Smart, Scale & Sustainable

Accelerating Market Share Gains

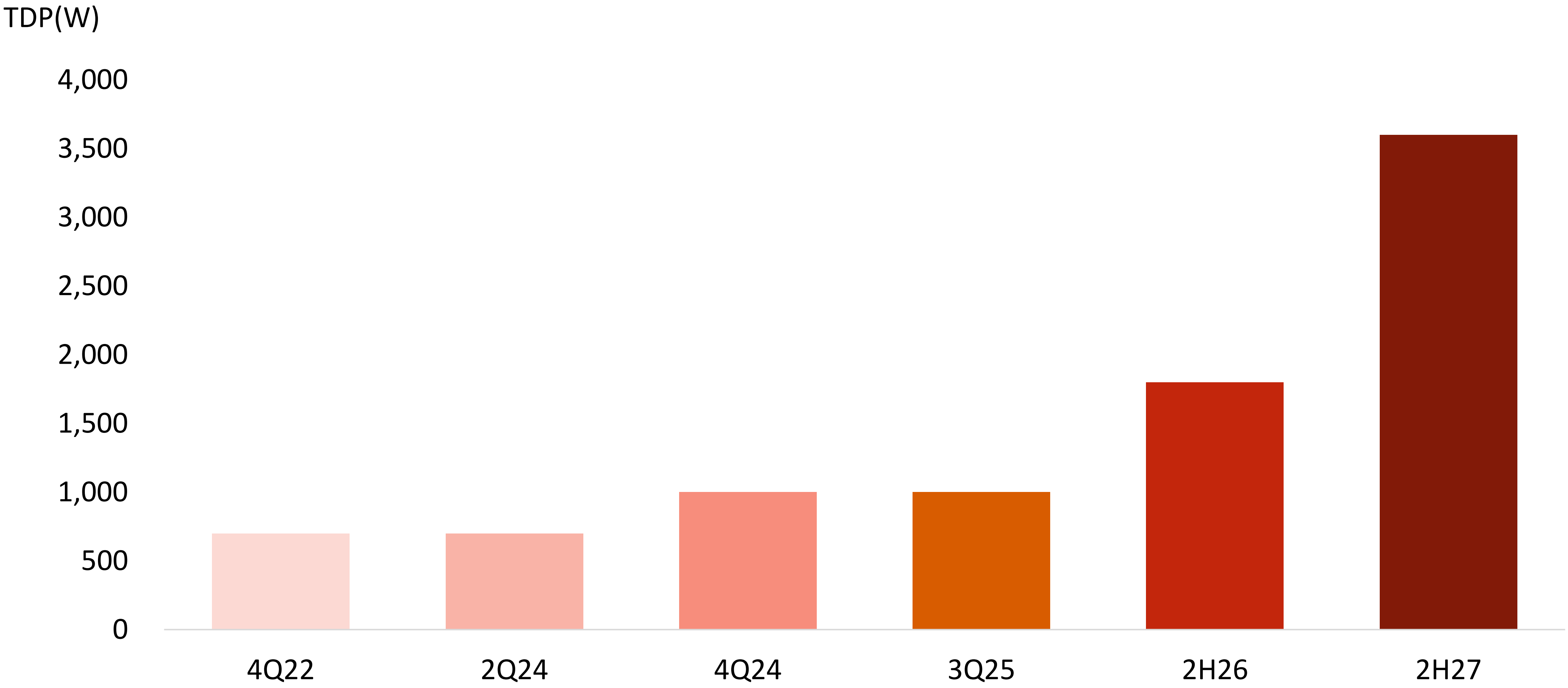


Source: company data, PSI

Potential Drivers from 12” Si and SiC

Capitalizing on the Power and Thermal Imperative

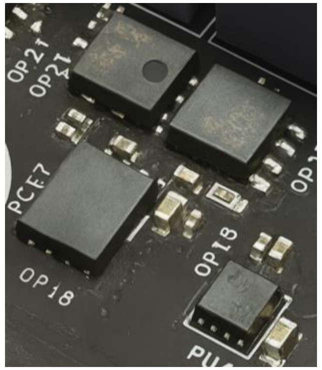
An unprecedented challenge to data center power and cooling infrastructure.



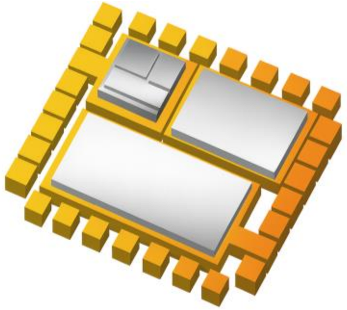
Source: company data, Nomura, GFHK

Dr. MOS Capturing Multi-market Growth

Traditional Design

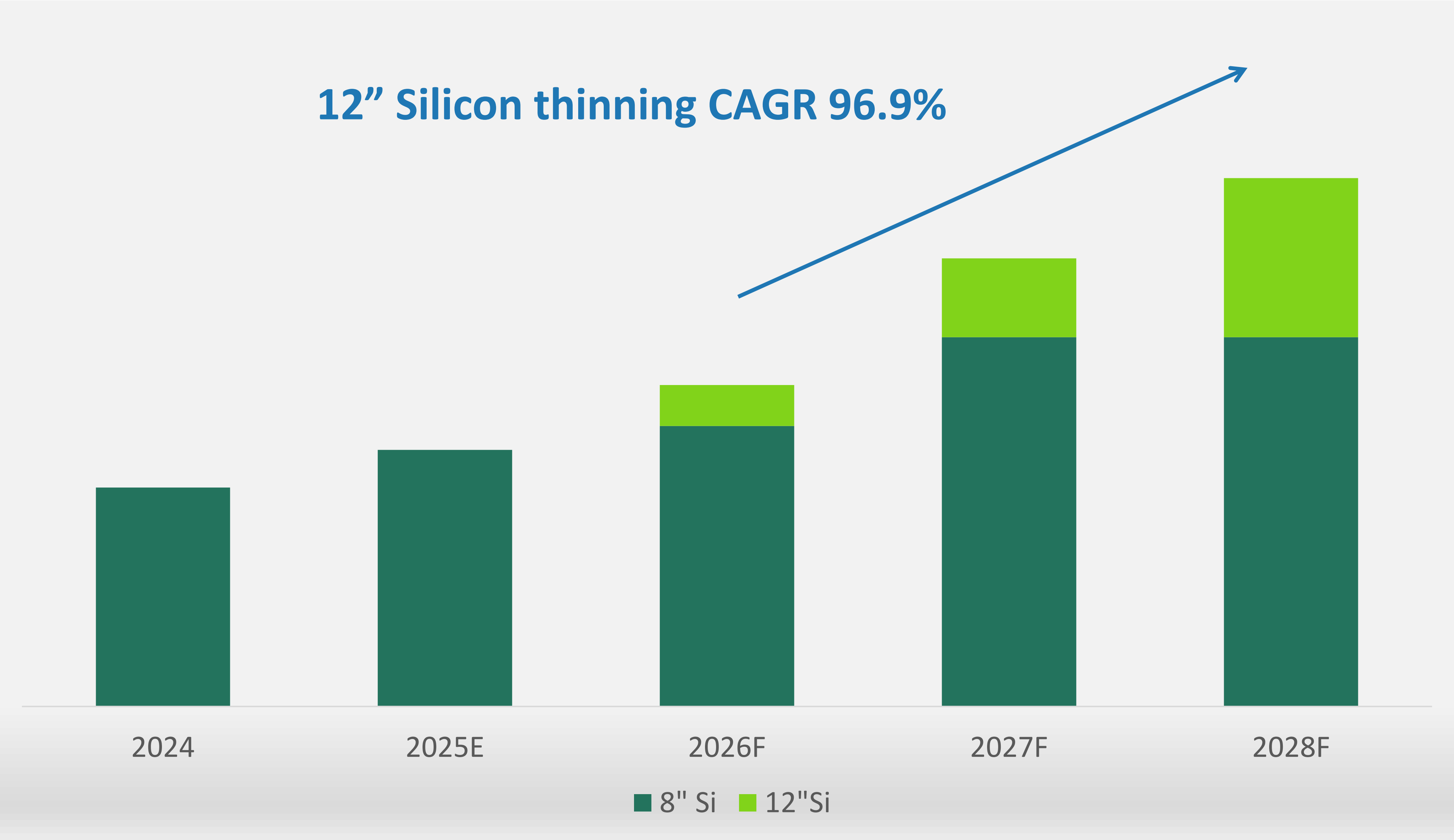


Driver MOSFET



High Density Power Module

Scaling Up 12-inch Si Thinning for Next-Gen



Beyond Silicon - Silicon Carbide Key Properties

High Performance Material

High Breakdown Field
- ~10× stronger than Si
- Thinner Drift Layer

Mechanical Strength
- Mohs ~9.2, 1.3X than Si
- High Hardness & Strength

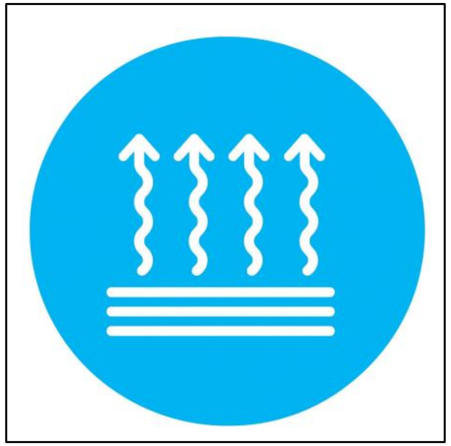
Optical Transmission
- SiC, best 0.4–2μm, strong & durable
- Glass, good in visible, weaker in IR

Thermal Conductivity
- 260–450 W/MK,
- 2~3x better than Si

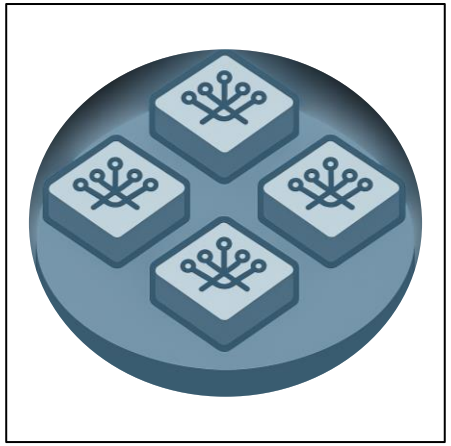
Source: company data, PSI

SiC New Era – Blooming Applications

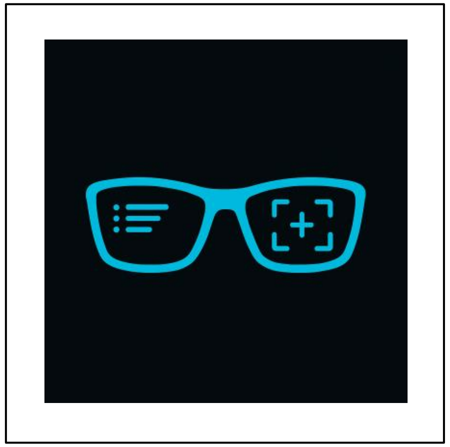
Heat Dissipater



IC Substrate



Specialty glass



Long Term Expansion Plan

Long Term Opportunities

USA

Drivers

- CHIPS Act driving
- Shorter lead times

Strategy

- Collaborate with local suppliers
- Premium pricing

Taiwan

Drivers

- Rising advanced-node demand
- Skilled talent and ecosystem

Strategy

- AI-driven fab
- Just-in-time delivery

India

Drivers

- Government promoting
- Global fabs investing

Strategy

- Partner with local fabs
- Modular lines for rapid scaling

Taiwan Expansion Plan Update

Hsinchu, hybrid fab

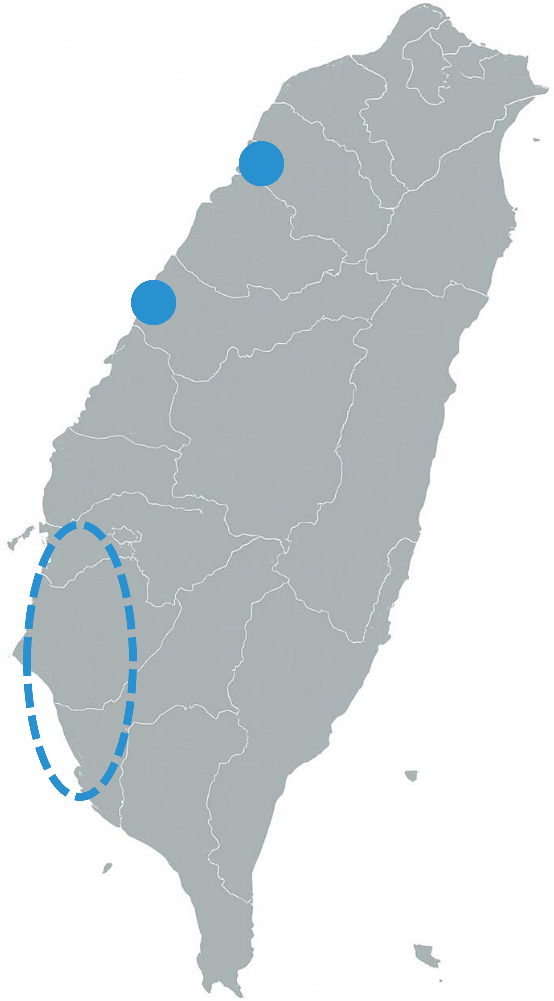
- Reclaim MP in 1998
- Thinning MP in 2005

Taichung, pure reclaim fab

- 1st fab MP in 2022
- 2nd fab under construction

Southern Taiwan

- Hub for Advanced node Manufacturing
- PSI is assessing the feasibility



Key Messages From PSI

Focused on Growth, Anchored by Discipline

- Advanced nodes and heterogeneous packaging accelerating reclaim demands
- Development in 12” power device thinning and new TIM for next-gen AI products
- Sustainable leadership and profitability via innovative and disciplined investments

Https://www.psi.com.tw
ir@psi.com.tw